	Type	Hits	Search Text	DBs
1	BRS	107	(encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and capacitor and ground adj (plate or plane or film or layer) and power adj (plate or plane or film or layer)	USPAT; JPO
2	BRS	51	(encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and decoupling adj capacitor and ground adj (plate or plane or film or layer) and power adj (plate or plane or film or layer)	USPAT; JPO
3	BRS	56	(encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and capacitor and ground adj (plate or plane or film or layer) and power adj (plate or plane or film or layer) not ((encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and decoupling adj capacitor and ground adj (plate or plane or film or layer) and power adj (plate or plane or film or layer))	USPAT; JPO
4	BRS	1950	(encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and capacitor and ground and power	USPAT; JPO
5	BRS	1	(encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and capacitor and ground and power	JPO

	Type	Hits	Search Text	DBs
6	BRS	2	(encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and capacit$ and ground and power	JPO
7	BRS	10	4967081.pn. or 4734818.pn. or 10070234.pn. or 11204699.pn. or 5095402.pn. or 5153710.pn. or 5283717.pn. or 5607883.pn. or 6330164.pn. or 5844307.pn.	USPAT; JPO
8	BRS	18	5283717.uref.	USPAT; JPO
9	BRS	360	(encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and capacitor and ground adj (plate or plane or film or layer) and power	USPAT; JPO
10	BRS	102	(encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and decoupling adj capacitor and ground adj (plate or plane or film or layer) and power	USPAT; JPO
11	BRS	102	(encapsul$ or mold) and (die or chip or semiconduct$ or IC) and decoupling adj capacitor and ground adj (plate or plane or film or layer) and power	USPAT; JPO
12	BRS	294	(die or chip or semiconduct$ or IC) and (lead or wire or metal$) and decoupling adj capacitor and ground adj (plate or plane or film or layer) and power	USPAT; JPO
13	BRS	2	5883428.pn. or 5825628.pn.	USPAT; JPO
14	BRS	12	5883428.uref. or 5825628.uref.	USPAT; JPO
15	BRS	3	5883428.pn. or 5825628.pn. or 5283717.pn.	USPAT; JPO

	Type	Hits	Search Text	DBs
16	BRS	11	4967081.pn. or 4734818.pn. or 10070234.pn. or 11204699.pn. or 5095402.pn. or 5153710.pn. or 5283717.pn. or 5607883.pn. or 6330164.pn. or 5844307.pn. or 5883428.pn.	USPAT; JPO
17	BRS	9	4734818.pn. or 10070234.pn. or 11204699.pn. or 5825628.pn. or 5283717.pn. or 5607883.pn. or 6330164.pn. or 5844307.pn. or 5883428.pn.	USPAT; JPO
18	BRS	36	(257/723 or 257/724 or 257/68 or 257/71) and (encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and capacitor and ground adj (plate or plane or film or layer) and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
19	BRS	28	(257/924 or 257/908 or 257/532 or 257/516) and (encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and capacitor and ground adj (plate or plane or film or layer) and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
20	BRS	6	(257/308 or 257/307 or 257/300 or 257/298) and (encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and capacitor and ground adj (plate or plane or film or layer) and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
21	BRS	6	(257/308 or 257/307 or 257/300 or 257/298) and (encapsul$ or mold) and (die or chip or semiconduct$ or IC) and (lead or wire or metal$) and capacitor and ground adj (plate or plane or film or layer) and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB